

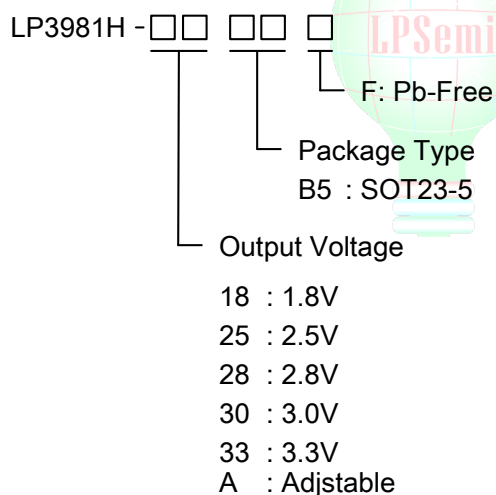
500mA Output, Low noise, Low-Dropout CMOS Linear Regulator

General Description

The LP3981H series low-dropout, low-power regulators offer a fast start-up and excellent line and load transient responses. A low ground current while at no load with chips enabled makes the devices attractive for battery-operate power systems. The LP3981H series also provides an active pull-down circuit to quickly discharge output load. Other features include short current limit, thermal protection and a low current consume shut-down mode.

The LP3981H is available in SOT23-5 packages.

Order Information



Features

- ◆ 2.5V~5.5V Input Voltage Range
- ◆ Low Dropout: 260mV @ 300mA
- ◆ 500mA Output Current
- ◆ High PSRR: -63dB at 1KHz
- ◆ <0.1uA Standby Current In Shutdown Mode
- ◆ TTL-Logic-Controlled Shutdown Input
- ◆ Ultra-Fast Response in Line/Load transient
- ◆ Current Limit and Thermal Shutdown Protection

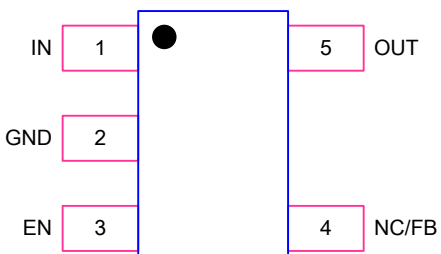
Applications

- ✧ Portable Media Players/MP3 players
- ✧ Cellular and Smart mobile phone
- ✧ LCD
- ✧ DSC Sensor
- ✧ Wireless Card

Marking Information

Device	Marking	Package	Shipping
LP3981H-33B5F	LPS 3EYWX	SOT23-5	3K/REEL
LP3981H-30B5F	LPS 3GYWX	SOT23-5	3K/REEL
LP3981H-28B5F	LPS 3HYWX	SOT23-5	3K/REEL
LP3981H-25B5F	LPS 3DYWX	SOT23-5	3K/REEL
LP3981H-18B5F	LPS 3CYWX	SOT23-5	3K/REEL
LP3981HAB5F	LPS 3AYWX	SOT23-5	3K/REEL
Marking indication: Y: Year code .W: W is week code. X: X is series number.			

Pin Descriptions

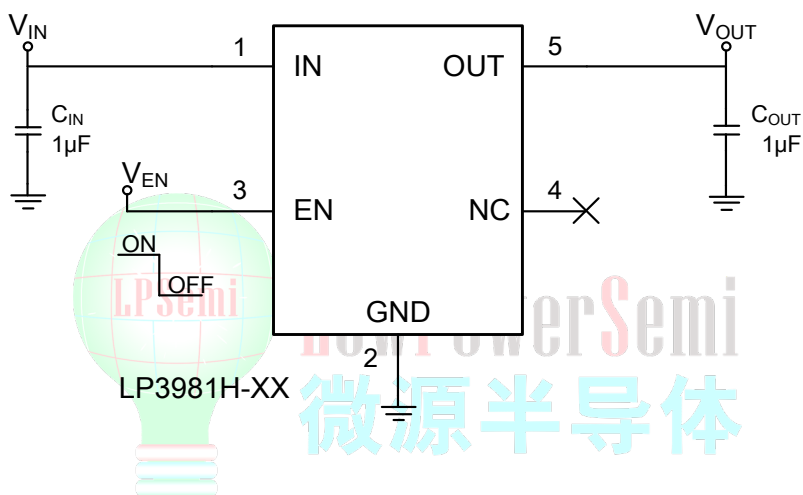
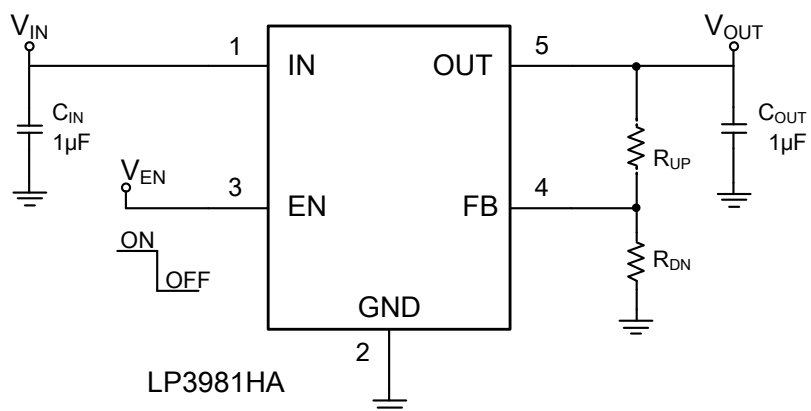
Package Type	Pin Configurations
SOT23-5	

Pin Description

Pin	Name	Description
1	IN	Power Supply Pin.
2	GND	Ground.
3	EN	Chip Enable (Active High). Note that this pin is high impedance. There should be a pull low 100k Ω resistor connected to GND when the control signal is floating.
4	NC	No Connect.
	FB	Feedback Pin The Reference Voltage is 0.8V
5	OUT	Output Pin.

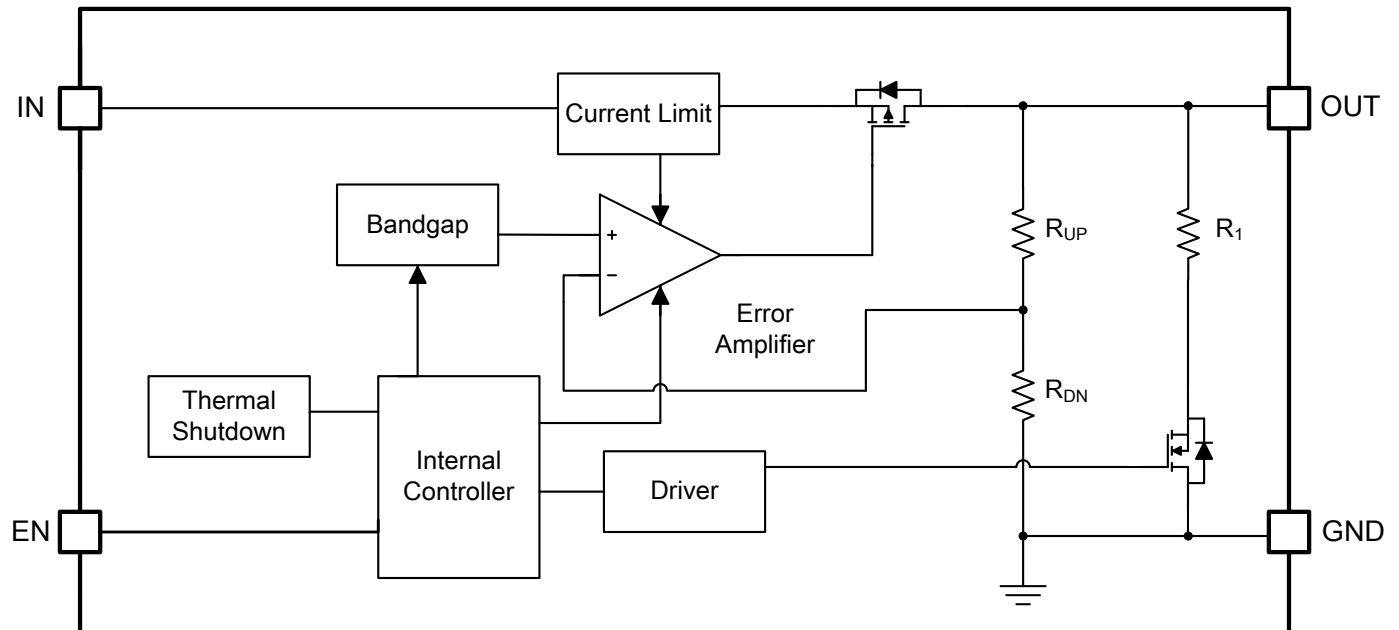


Typical Application Circuit





Functional Block Diagram



Absolute Maximum Ratings

✧ Supply Input Voltage	-----	-0.3V to 6V
✧ Other Pins Voltage	-----	-0.3V to 6V
✧ Power Dissipation, P_D @ $T_A=25^{\circ}\text{C}$ SOT23-5	-----	400mW
✧ Package Thermal Resistance SOT23-5, θ_{JA}	-----	$250^{\circ}\text{C}/\text{W}$
✧ Lead Temperature (Soldering, 10 sec.)	-----	260°C
✧ Storage Temperature Range	-----	-60°C to 125°C

ESD Susceptibility

✧ HBM (Human Body Model)	-----	2KV
✧ MM(Machine-Model)	-----	200V

Recommended Operating Conditions

✧ Supply Input Voltage	-----	2.5V to 5.5V
✧ EN Input Voltage	-----	0V to 5.5V
✧ Operation Junction Temperature Range	-----	-40°C to 125°C
✧ Operation Ambient Temperature Range	-----	-40°C to 85°C

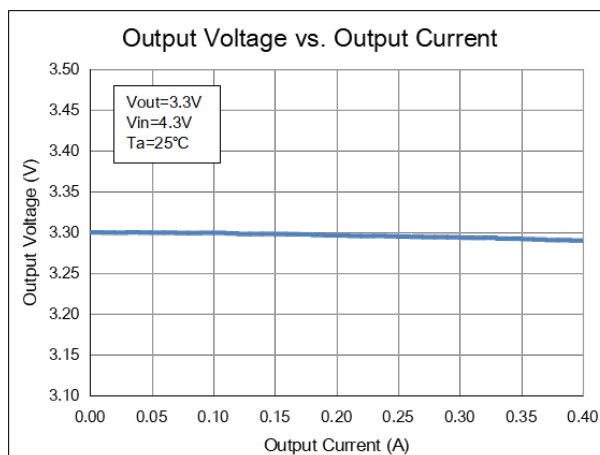
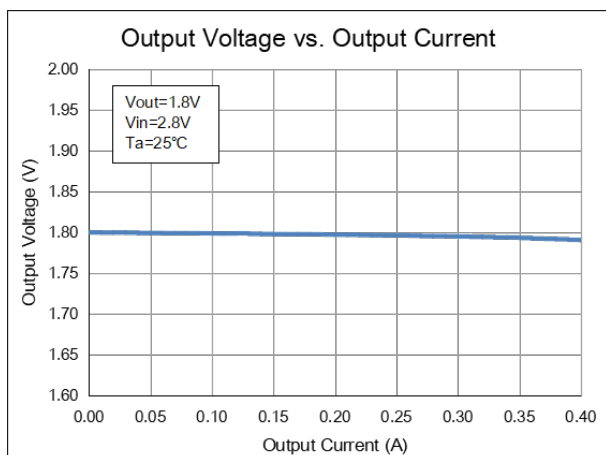
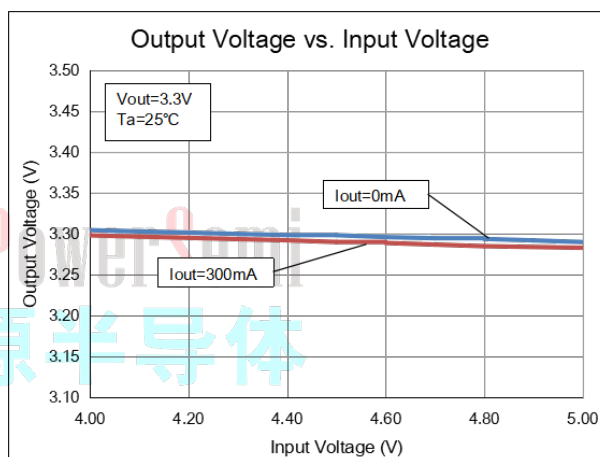
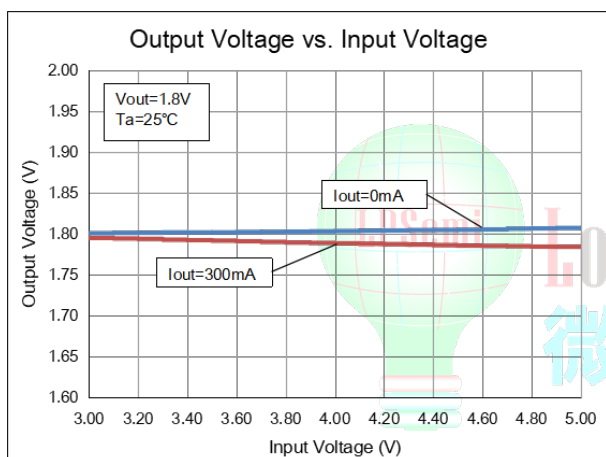
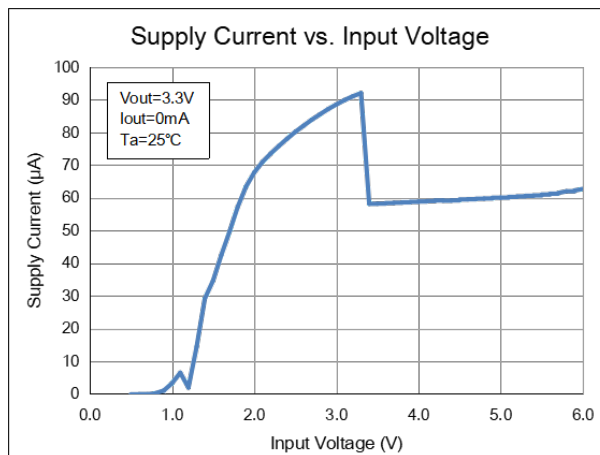
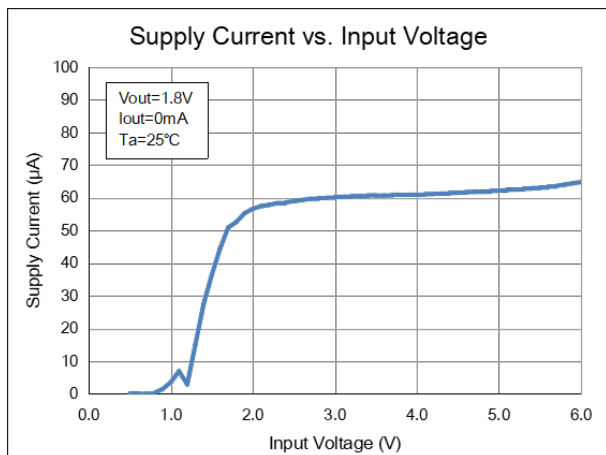
Electrical Characteristics

($V_{IN}=V_{OUT} + 1V$, $C_{IN}=C_{OUT}=1\mu F$, $T_A=25^\circ C$, unless otherwise specified)

Parameter		Symbol	Test Conditions	Min	Typ	Max	Units
Output Voltage Accuracy		ΔV_{OUT}	$I_{OUT}=1mA$	-2	--	+2	%
Maximum Output Current		I_{max}	$V_{IN}>2.8V$		500		mA
Current Limit		I_{LIM}	$R_{LOAD}=1\Omega$		750		mA
Adjustable voltage reference		V_{FB}	LP3981HA , $I_{OUT}=1mA$	0.784	0.8	0.816	V
Quiescent Current		I_Q	$(V_{OUT}+1V)<V_{IN}<5.5V$, $V_{OUT}=1.8V$		58		μA
			$(V_{OUT}+1V)<V_{IN}<5.5V$, $V_{OUT}=3.3V$		62		μA
Dropout Voltage		V_{DROP}	$I_{OUT}=300mA$, $V_{OUT}=1.8V$		750		mV
			$I_{OUT}=300mA$, $V_{OUT}=2.8V$		280		mV
			$I_{OUT}=300mA$, $V_{OUT}=3.3V$		260		mV
Line Regulation		$\frac{\Delta V_{OUT}}{\Delta V_{IN} \times V_{OUT}}$	$V_{OUT}=1.8V$, $I_{OUT}=1mA$, $V_{IN}=2.8V$ to 5.5V			1	%
			$V_{OUT}=2.8V$, $I_{OUT}=1mA$, $V_{IN}=3.8V$ to 5.5V			0.5	%
			$V_{OUT}=3.3V$, $I_{OUT}=1mA$, $V_{IN}=4.3V$ to 5.5V			0.5	%
Load Regulation		$\frac{\Delta V_{OUT}}{V_{OUT}}$	$V_{OUT}=1.8V$, $I_{OUT}=1mA$ to 200mA			2	%
			$V_{OUT}=2.8V$, $I_{OUT}=1mA$ to 200mA			1.5	%
Standby Current		I_{STBY}	$V_{EN}=0V$, Shutdown		0.1	1	μA
EN Input Bias Current		I_{IBSD}	$V_{EN}=1V$		0.6	2	μA
EN Threshold	Logic-Low Voltage	V_{IL}	$V_{IN}=(V_{OUT}+1V)$ to 5.5V, Shutdown			0.4	V
	Logic-High Voltage	V_{IH}	$V_{IN}=(V_{OUT}+1V)$ to 5.5V, Start-Up	1.4			V
Output Noise Voltage			10Hz to 100kHz, $I_{OUT}=200mA$		100		$\mu VRMS$
Power Supply Rejection Rate	f=1KHz	PSRR	$C_{OUT}=1\mu F$, $I_{OUT}=50mA$, $V_{OUT}=1.8V$		-64		dB
	f=10kHz				-54		dB
	f=1KHz		$C_{OUT}=1\mu F$, $I_{OUT}=50mA$, $V_{OUT}=3.3V$		-63		dB
	f=10kHz				-56		dB
Thermal Shutdown Temperature		T_{SD}	$I_{OUT}=0.1mA$		160		$^\circ C$

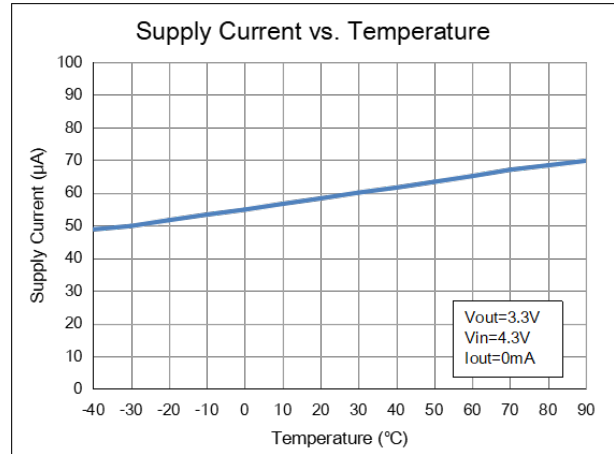
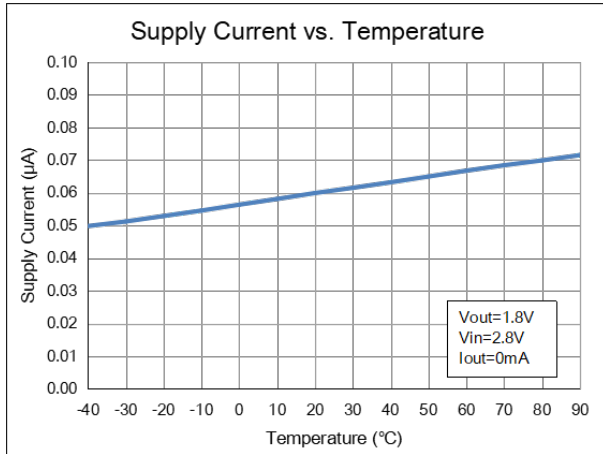
Typical Operating Characteristics

($C_{IN}=C_{OUT}=1\mu F$, $T_A=25^\circ C$, unless otherwise specified)



Typical Operating Characteristics

($C_{IN}=C_{OUT}=1\mu F$, $T_A=25^\circ C$, unless otherwise specified)



Applications Information

The LP3981H series is a low input, low quiescent current and low dropout linear regulator. Additionally, the device contains current limit, soft-start, active pull-down and under-voltage lockout circuit. The internal current limit circuitry protects the device from damage at fault condition. For example, the output of device short to GND or load current is larger than the limited current threshold of the device. During these fault condition, the device sources a fixed amount of current that depends on output voltage. And the internal soft-start circuitry helps protect the supply voltage from the inrush current. The active pull-down circuitry works at which EN pin is in a logic low level, In this case, the voltage of output will decrease.

Under-Voltage Lockout

The LP3981H use an under-voltage lockout circuit. As the input voltage lower than the UVLO threshold voltage (typically 1.5V), the device is turned off. With the input voltage reaches above the UVLO threshold voltage, the device turns the pass elements on.

Start-up Function Enable Function

The LP3981H automatically adjusts the soft-start current to protect input supply from the inrush current, it is approximately equal to the sum of load current and output capacitor charge current.

The enable pin is active high. The internal pass element is turned on when the enable pin voltage is higher than the EN logic high threshold voltage, and the pass element is turned off when the enable pin voltage is lower than the EN logic low threshold voltage. In this case, the device is in an ultralow current shutdown mode.

Active Discharge

The active pull-down circuit has internal pull-down MOSFET that connect a 120Ω resistor to GND in order to quickly discharge the load. The discharge circuit is active when the EN pin is logic low level and thermal shutdown mode.

Thermal Considerations

When the operation junction temperature exceeds T_{SD} , the OTP circuit turns the pass element off. The pass element turns on again after the junction temperature cools approximately 25°C. For continue operation, do not exceed absolute maximum operation junction temperature 125°C.

The power dissipation definition in device is :

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} + V_{IN} \times I_Q$$

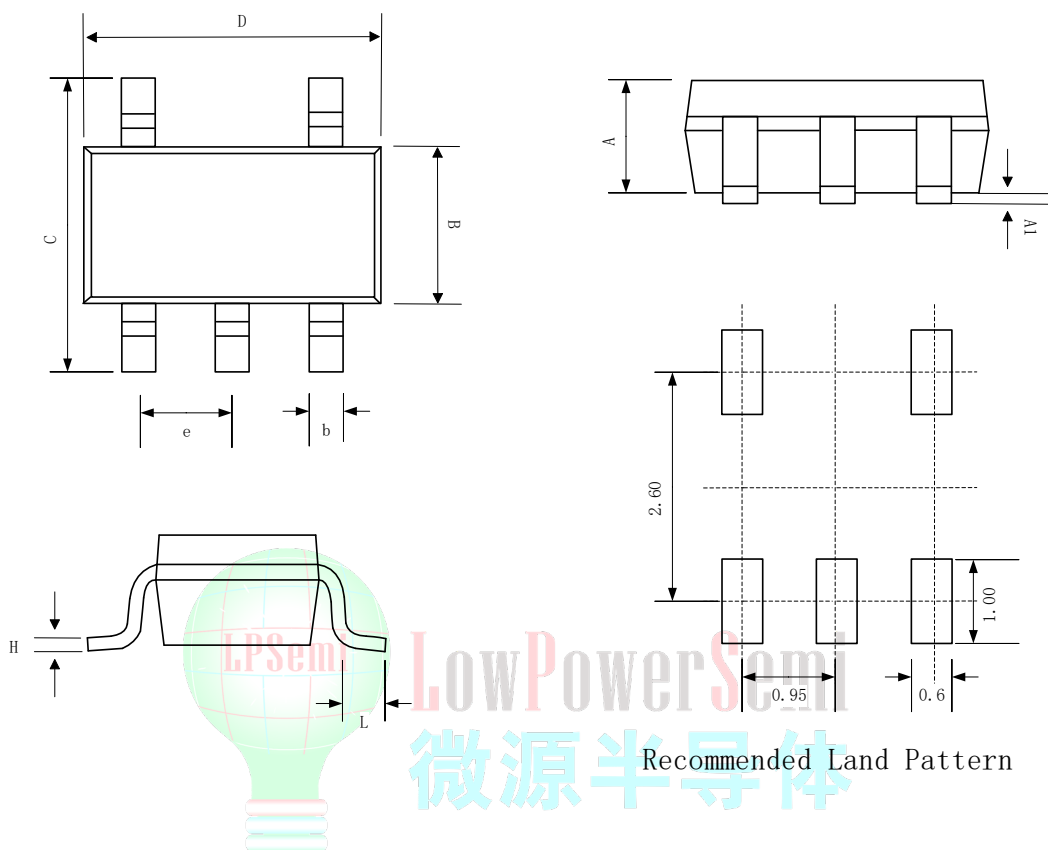
The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junction to ambient.

The maximum power dissipation can be calculated by following formula:

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_A}{\theta_{JA}}$$

Packaging Information

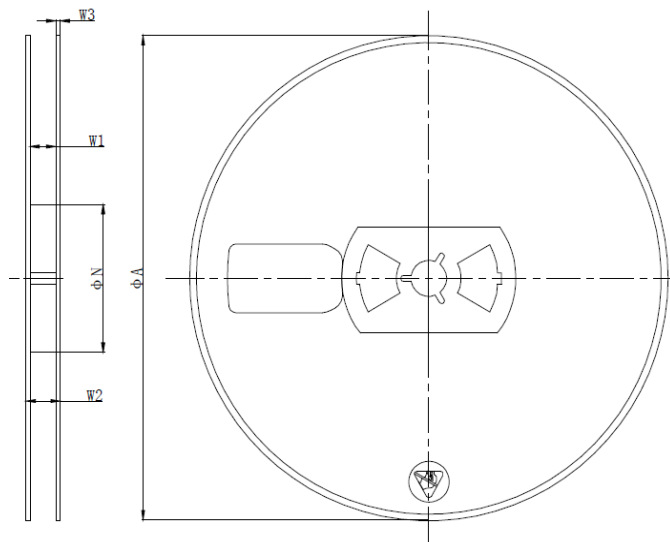
SOT23-5



SYMBOL	Dimensions In Millimeters		
	MIN	NOM	MAX
A	0.889	1.100	1.295
A1	0.000	0.050	0.152
B	1.397	1.600	1.803
b	0.28	0.35	0.559
C	2.591	2.800	3.000
D	2.692	2.920	3.120
e	0.95BSC		
H	0.080	0.152	0.254
L	0.300	0.450	0.610

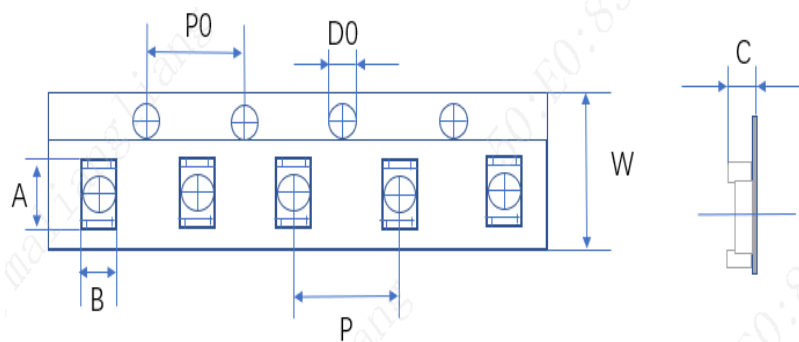
Tape and Reel Information

REEL DIMENSIONS



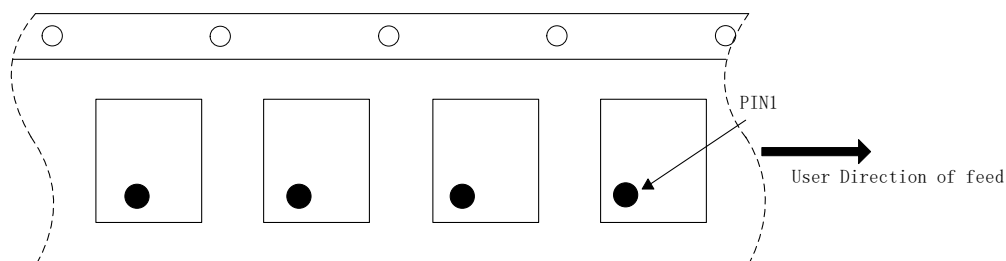
SYMBOL	Dimensions In Millimeters		
	MIN	NOM	MAX
ΦA	176.00	180.00	184.00
W2	10.00	12.00	14.00

TAPE DIMENSIONS



SYMBOL	Dimensions In Millimeters		
	MIN	NOM	MAX
A	3.00	3.20	3.40
B	3.06	3.26	3.46
P0	3.90	4.00	4.10
P	3.90	4.00	4.10
D0	1.35	1.50	1.55
W	7.70	8.00	8.30
C	1.20	1.40	1.60

PIN1 AND TAPE FEEDING DIRECTION



Classification of IR Reflow Profile

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak		
Temperature Min(T_{SMIN})	100°C	150°C
Temperature Max(T_{SMAX})	150°C	200°C
Time(T_S) from (T_{SMIN} to T_{SMAX})	60~120 seconds	60~120 seconds
Ramp-up rate (T_L to T_P)	3°C/second max	3°C/second max
Liquidous temperature(T_L)	183°C	217°C
Time(t_L) maintained above T_L	60~150 seconds	60~150 seconds
Peak package body temperature (T_P)	For users T_P must not exceed the Classification temp in Table 1. For suppliers T_P must equal or exceed the Classification temp in Table 1.	For users T_P must not exceed the Classification temp in Table 2. For suppliers T_P must equal or exceed the Classification temp in Table 2.
Time(t_P)* within 5°C of the specified classification temperature(T_C), see Figure1	20* seconds	30* seconds
Ramp-down rate (T_P to T_L)	6°C/second max	6°C/second max
Time 25°C to peak temperature	6 minutes max	8minutes max
* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.		

Table 1 Sn-Pb Eutectic Process - Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 Pb-Free Process - Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350~2000	Volume mm ³ ≥350
<1.6mm	260°C	260°C	260°C
1.6mm~2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

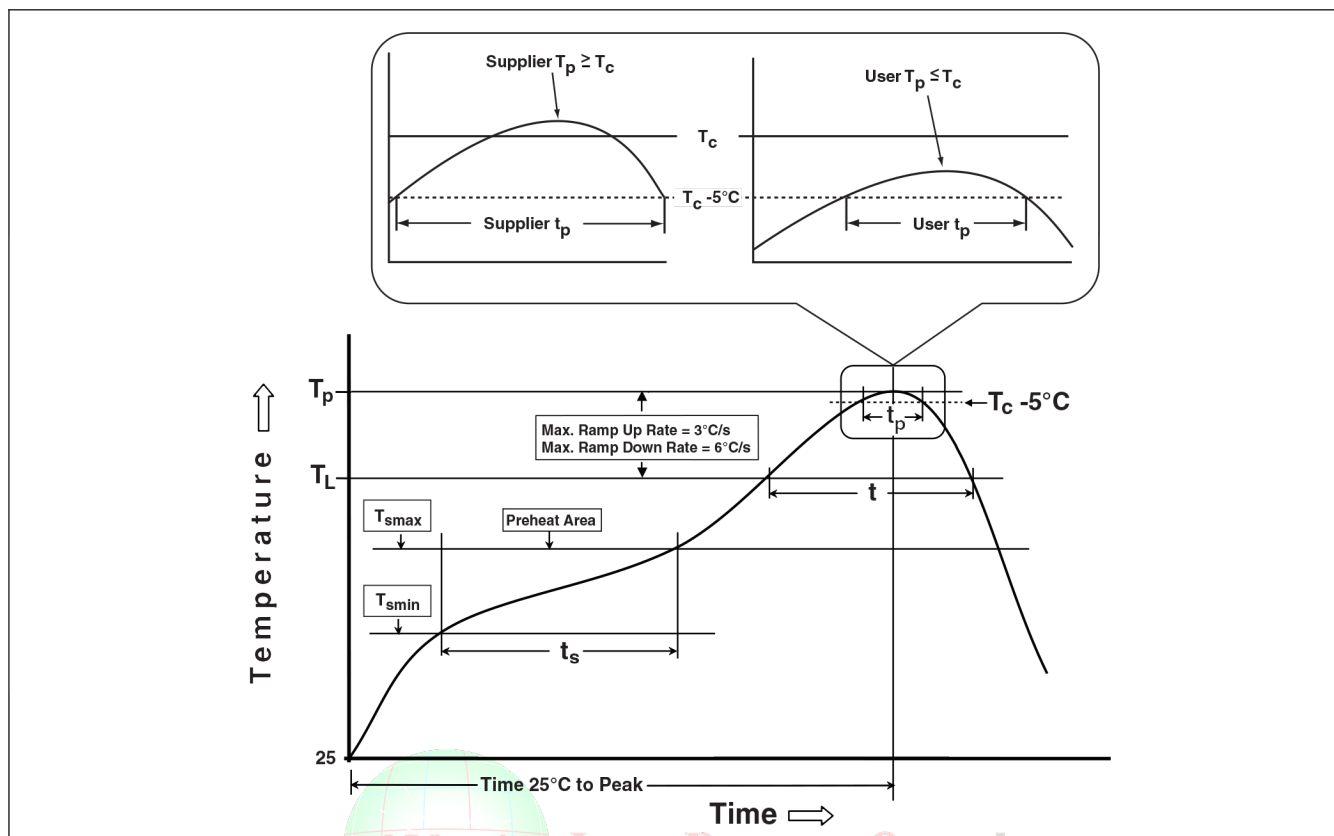


Figure1 Classification Profile (Not to scale)

Products conform to “JEDEC J-STD-020C” standards;

Products shipped conform to “RoHS” standards;

Moisture Sensitivity Level: MSL3 (CONDITION: $\leq 30^\circ\text{C}/60\%\text{RH}$ 、Time control:168 hours) ;